

Radiation response of *RADMON* sensors

T. Wijnands (TS/LEA), C. Pignard (TS/LEA)

NMRC Radfets 100 – 400 – 1000 nm

Toshiba TC554001AF-70 SRAM

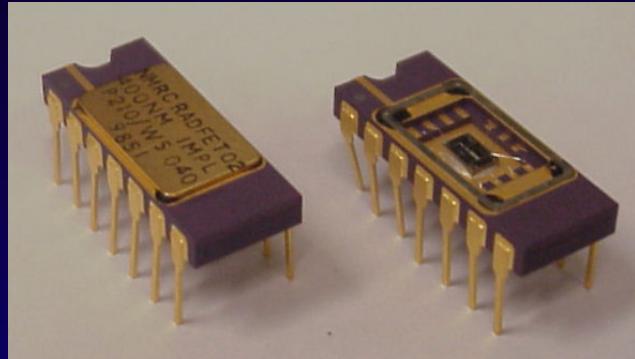
SIEMENS BPW34FS – PIN diode

Acknowledgements :

UCL Louvain-La-Neuve, PSI Villingen, TSL Uppsala, CIS-BIO (CEA Saclay),
PROSPERO (CEA-Valduc), A. Jaksic (Tyndall/NMRC)

Radiation Sensors

- ***RADFET***
 - Measure trapped charge in gate oxide
 - At constant current : ΔV proportional to **Total Ionising Dose**
- ***Static RAM***
 - Measure radiation induced voltage spikes over a reversed biased p-n junction
 - Number of “0-1 or 1-0” in SRAM proportional to the **hadron fluence ($E > 20$ MeV)**
- ***P-I-N Diode***
 - Measure conductivity variation at high forward injection
 - At constant current : ΔV proportional to **1 MeV eq. neutron fluence**



NMRC 300/50 400 nm



TOSHIBA TC554001AF-70L



SIEMENS BPW34

NMRC Radfets - Electrical properties at 0 Gy

Manufacturer	NMRC	NMRC	NMRC
Oxide	1000 nm	400 nm	100 nm
Type	300/50 W/L	300/50 W/L	300/50 W/L
Readout Current	8.7 μ A	8.7 μ A	8.7 μ A
Threshold voltage	5.43 V	1.57 V	2.72 V
Temp Coefficient	-1.6 mV/ $^{\circ}$ C	-0.9 mV/ $^{\circ}$ C	-0.7 mV/ $^{\circ}$ C
Co-60 sensitivity	215 mV/Gy	65 mV/Gy	2.4 mV/Gy

Die size 1 mm x 1 mm
250 mm Kovar lid (Ni, Co, Fe)

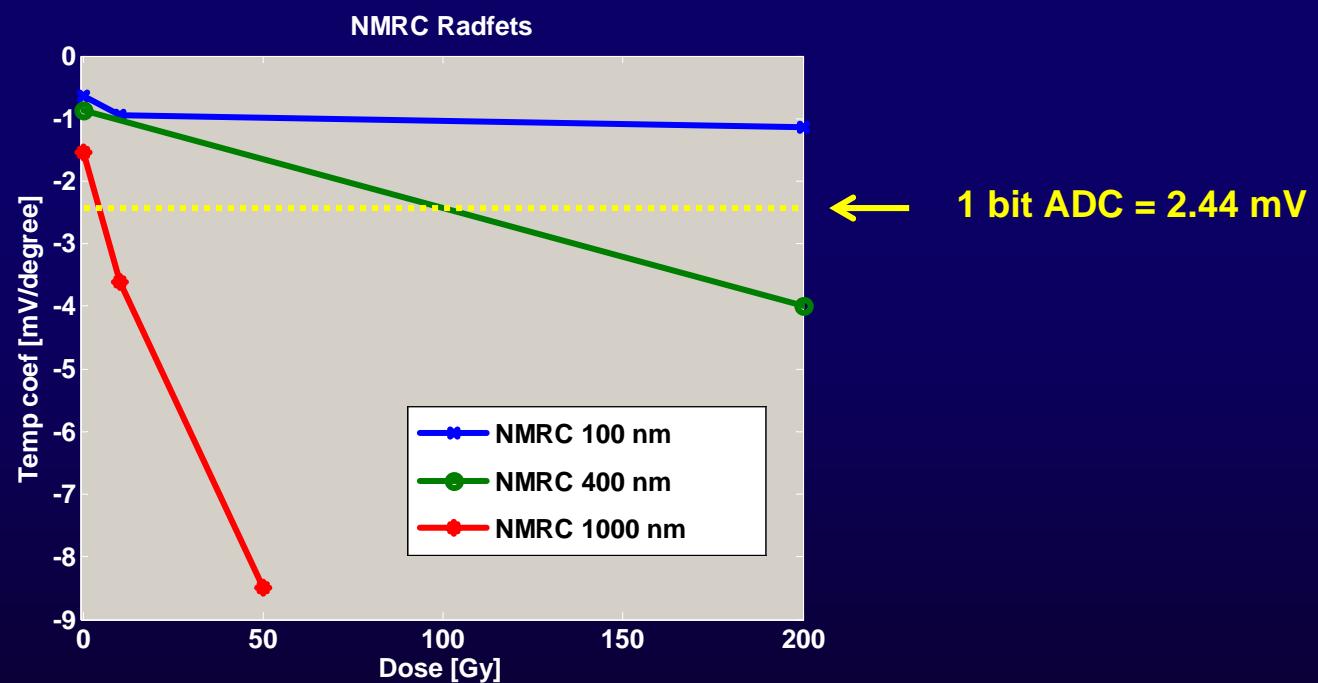
NMRC Radfets - Readout design

RADMON design choice : TID tolerance = 200 Gy

- ⇒ CMOS analog switching at maximum $V_{dd} = 10 \text{ V}$
- ⇒ 12 bit ADC at 10 V (2.44 mV/bit)
- ⇒ Maximum ΔV under irradiation :
 - 100 nm : $\Delta V = 10 \text{ V} - 2.72 \text{ V} = 7.28 \text{ V}$ (3 kGy)
 - 400 nm : $\Delta V = 10 \text{ V} - 1.57 \text{ V} = 8.43 \text{ V}$ (130 Gy)
 - 1 μm : $\Delta V = 10 \text{ V} - 5.43 \text{ V} = 4.57 \text{ V}$ (21 Gy)
- ⇒ Resolution :
 - 100 nm : 1 bit = 100 rad
 - 400 nm : 1 bit = 3.8 rad
 - 1 μm : 1 bit = 1.1 rad

NMRC Radfets - Thermo compensation

Oxide Thickness	1000 nm	400 nm	100 nm
Temp Coeff 0Gy	-1.6 mV/ $^{\circ}$ C	-0.9 mV/ $^{\circ}$ C	-0.7 mV/ $^{\circ}$ C
Temp Coeff 200 Gy	< -10 mV/ $^{\circ}$ C	-4 mV/ $^{\circ}$ C	-1.14 mV/ $^{\circ}$ C
Co-60 sensitivity	215 mV/Gy	65 mV/Gy	2.4 mV/Gy

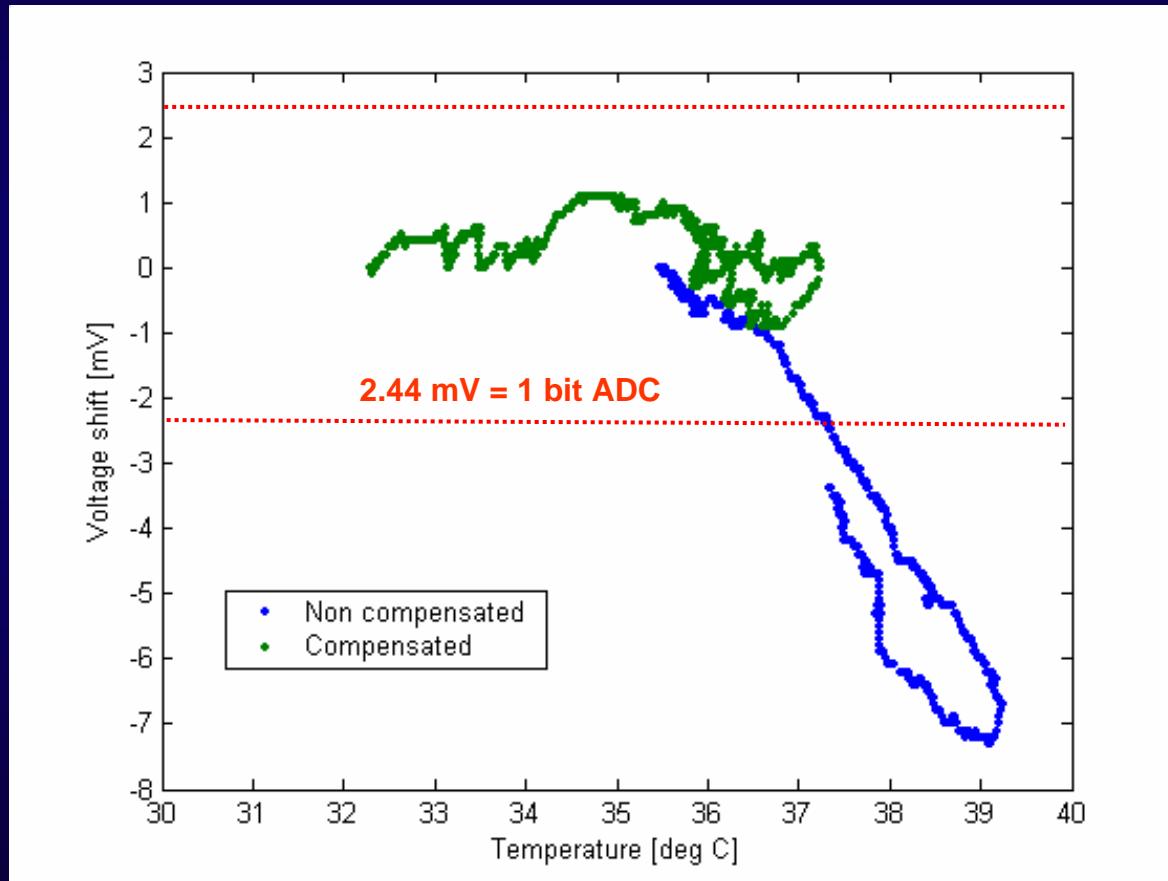


5th LHC Radiation Day

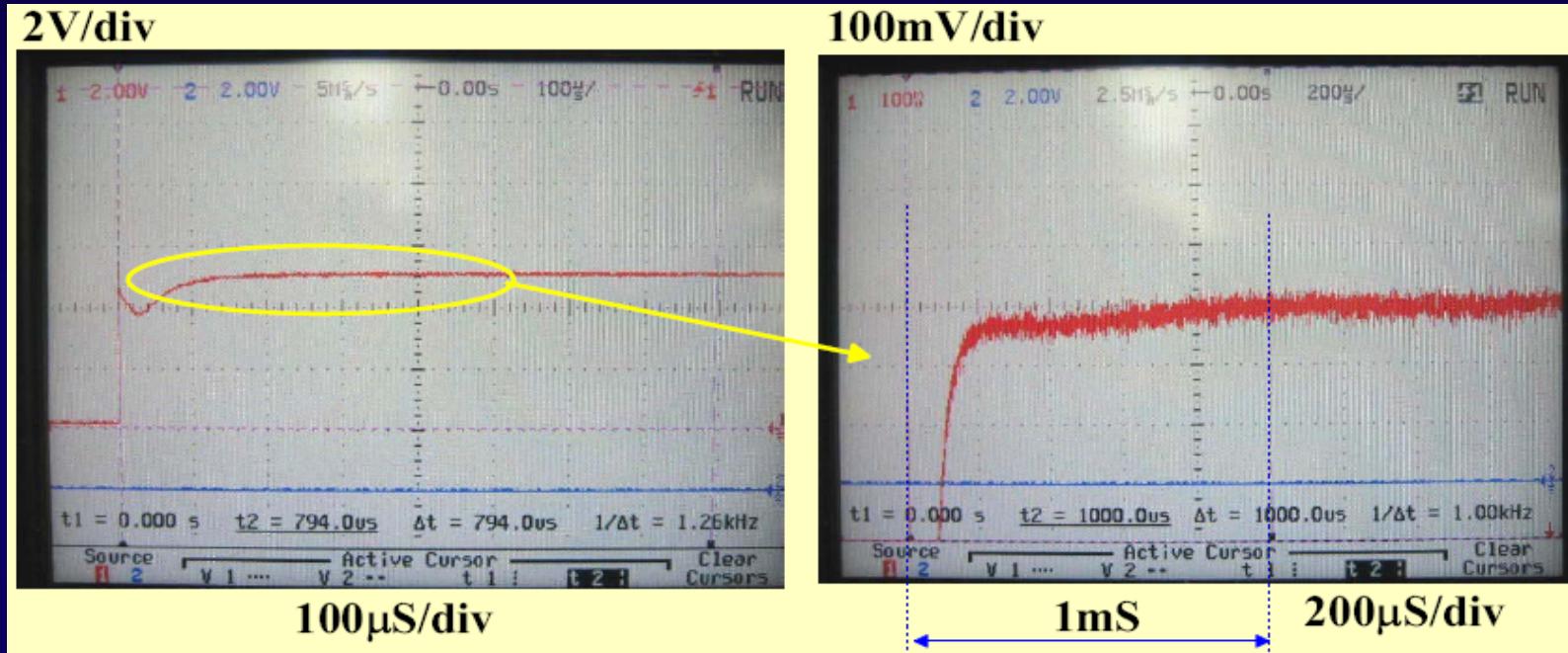
Co-60

RADMON - Thermo compensation in practice

NMRC RADFET 1000 nm (non irradiated device)

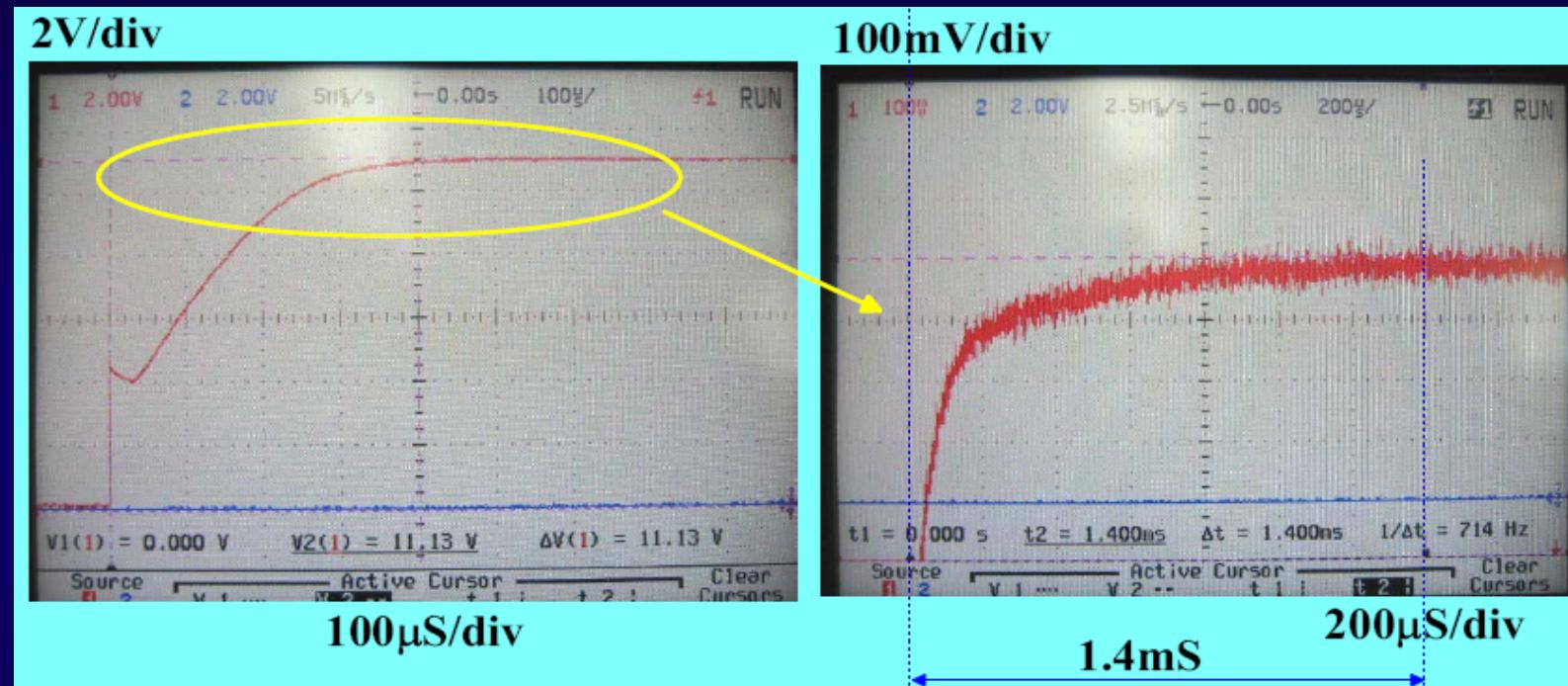


NMRC Radfets - Voltage Rise time at 0 Gy



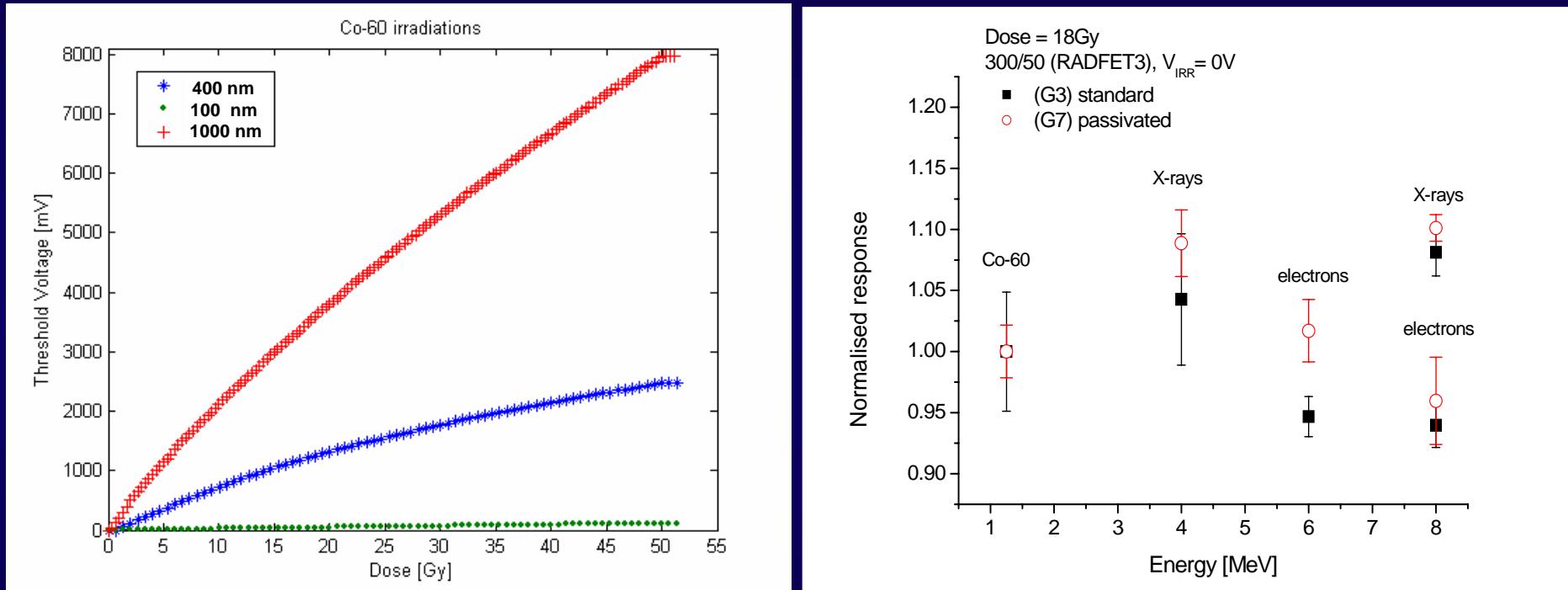
- NMRC Radfet 1000 nm
- Readout current 8.7 μA
- Short circuit : CMOS analog switch (TC4S66F Toshiba)

NMRC Radfets - Voltage Rise time at 50 Gy



- NMRC Radfet 1000 nm
- Readout current 8.7 μ A
- Short circuit : CMOS analog switch (TC4S66F Toshiba)

NMRC Radfets : energy response for photons

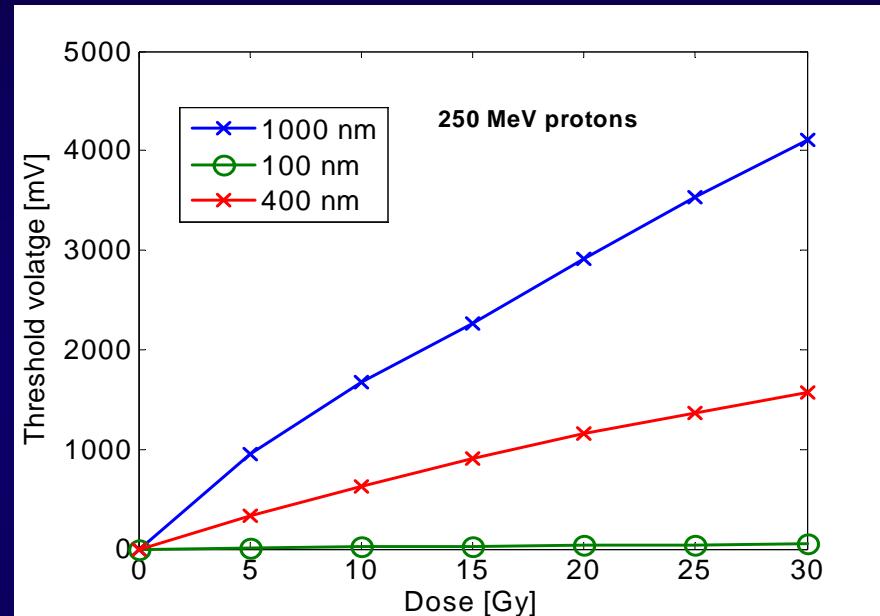


- Co-60 $\langle E \rangle = 1.25$ MeV
- Dose rate 50 Gy/hr
- ZTC readout

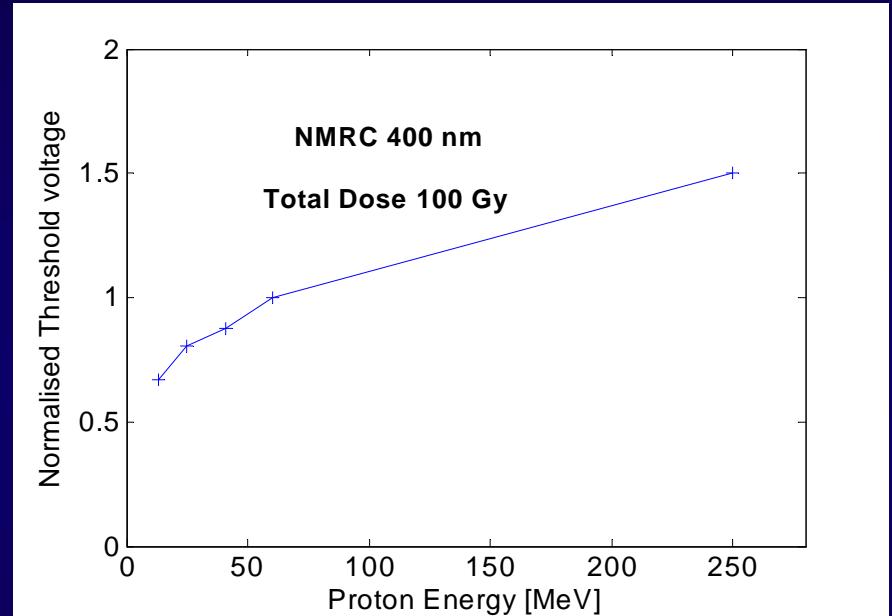
- NMRC Radfet 400 nm

Courtesy A. Jaksic (Tyndall)

NMRC Radfets : energy response for protons (1)

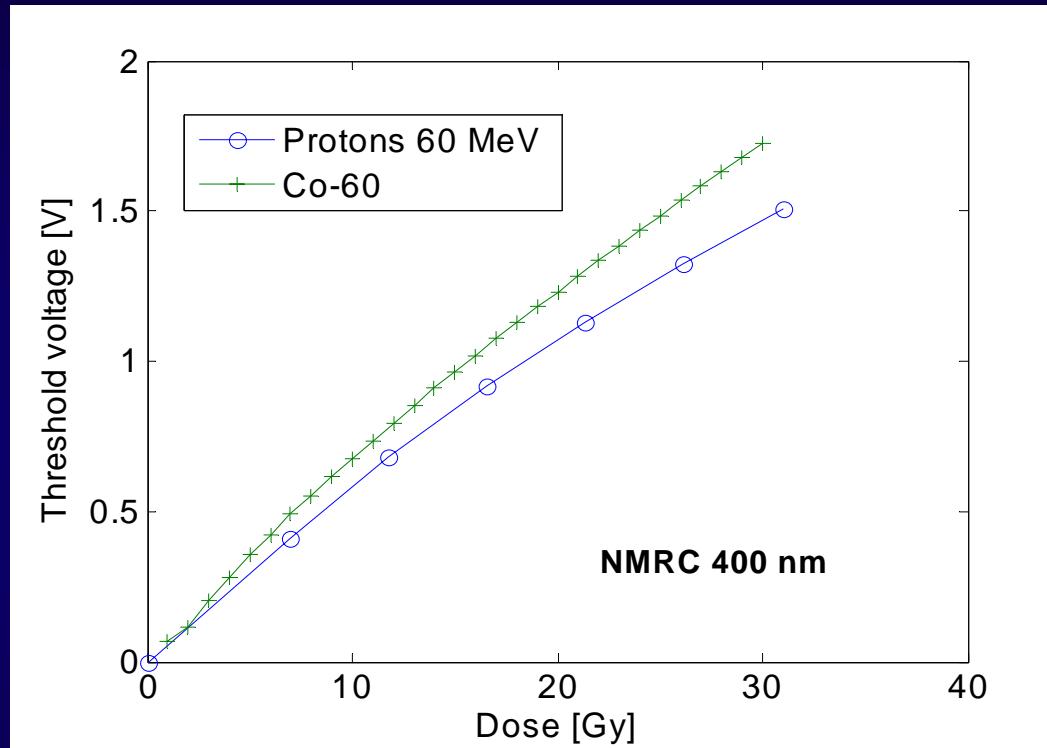


- Proton flux : $7 \cdot 10^7 \text{ cm}^{-2}$
- Thermo compensated (ZTC) readout

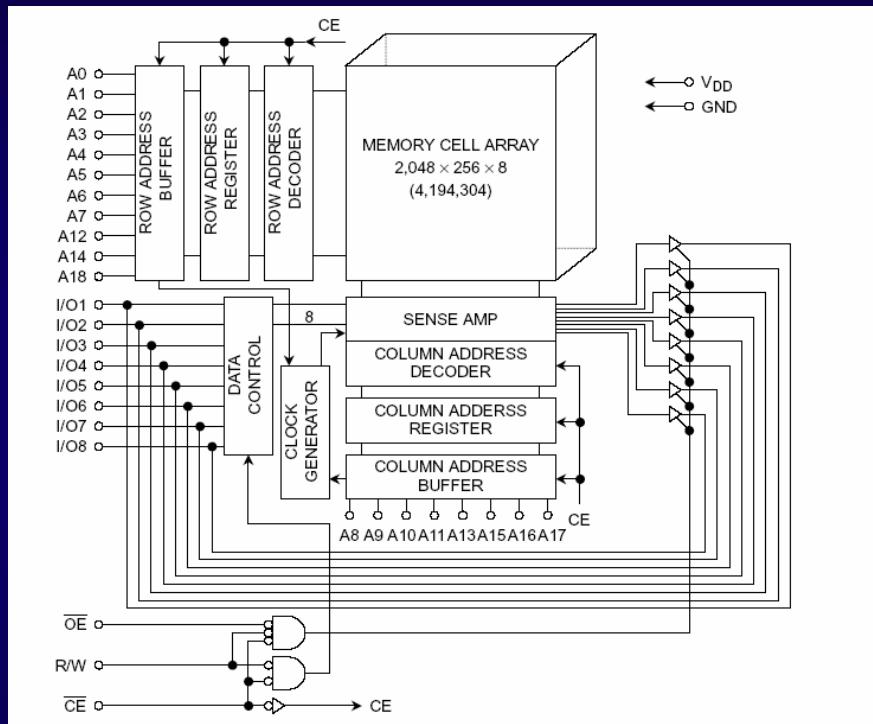


- Normalisation : 60 MeV protons

NMRC Radfets : energy response for protons (2)



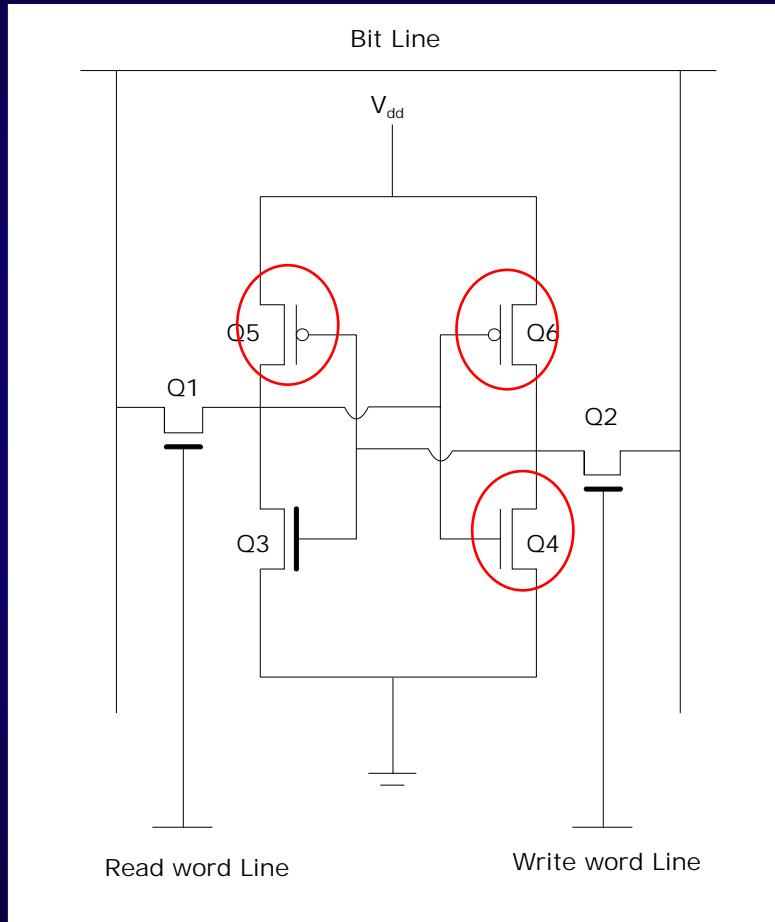
SEU counter – SRAM cell layout



Toshiba TC554001AF-70L

- 0.4 μm technology
- 3 – 5 V operation
- 4 Mbit (524288 words x 8 bits)
- grid arrangement 8192 x 512
- min cycle time 70 ns

SEU counter - 6 T SRAM cell 0.4 μm



Toshiba TC554001AF-70L

- Asymmetric SRAM cell
- $V_{dd} = 3$ or 5 V operation
- 3 TFTs, 3 bulk transistors
- Read at 3 V if :
 $\beta(Q3)/\beta(Q1) > 3.0$
- Write at 3 V if :
 $\beta(Q4)/\beta(Q2) < 0.1$

SEU counter – Radiation effects

$$Q_{\text{crit}} = C_{\text{node}} V_{\text{dd}} + I_{\text{restore}} / f$$

SEU if $Q > Q_{\text{crit}}$

Q = radiation induced charge

C_{node} = capacity of the node

I_{restore} = current restoring transistor

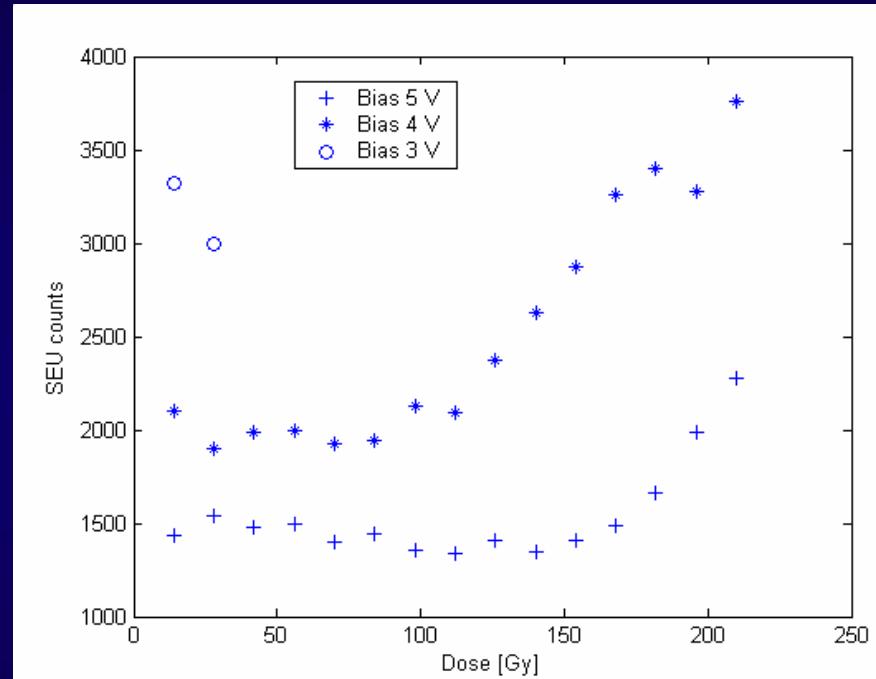
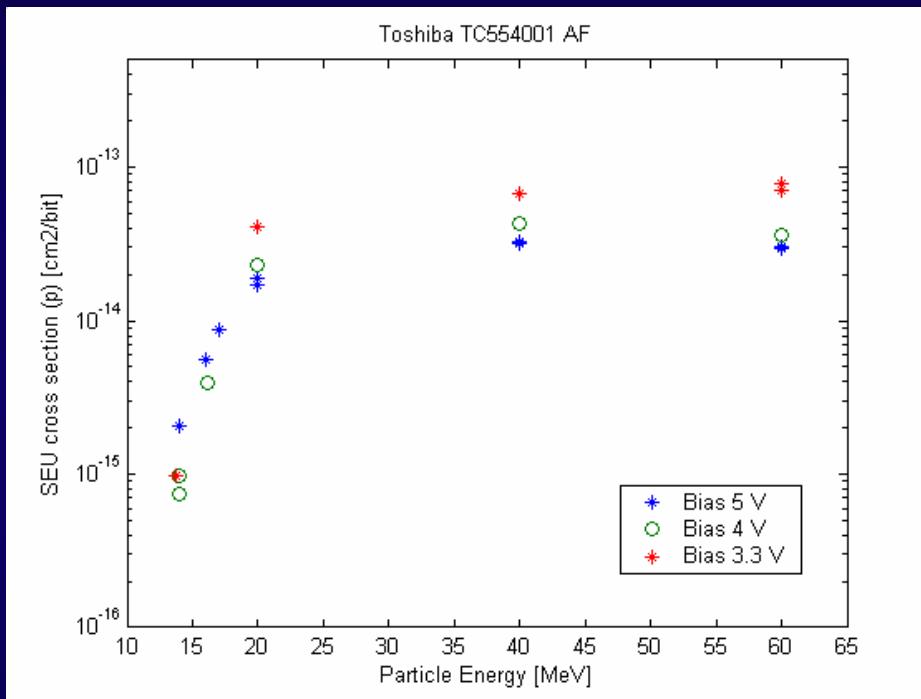
f = frequency of event

Effect of lowering the bias V_{dd} :

- SEU sensitivity **increased**
- TID tolerance is **decreased**

(writing more difficult because $\beta(Q4)/\beta(Q2)$ increased)

SEU counter – Proton irradiation

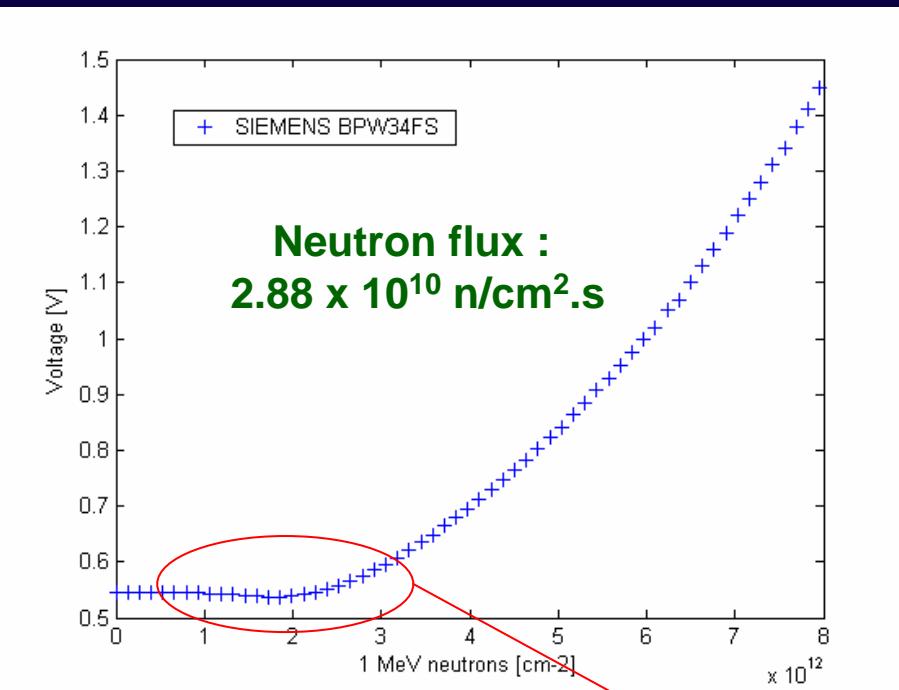


60 MeV protons

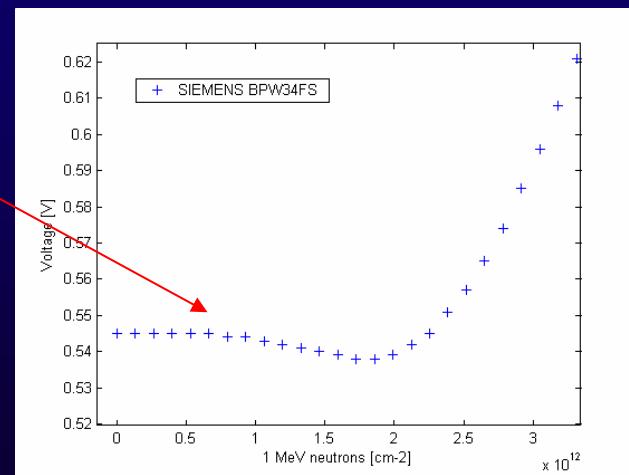
Pin Diode - BPW34FS key characteristics

- Temperature coefficient :
 - $2.4 \text{ mV/}^\circ\text{C}$ vs $2.5 \text{ mV/}^\circ\text{C}$ (after $5 \cdot 10^{12} \text{ n/cm}^2$)
- Linear dependence to 1 MeV neutron fluence
 - fluence > $4 \cdot 10^{12} \text{ n/cm}^2$
- Annealing at room temperature very small

PIN diode – 1 MeV neutron response

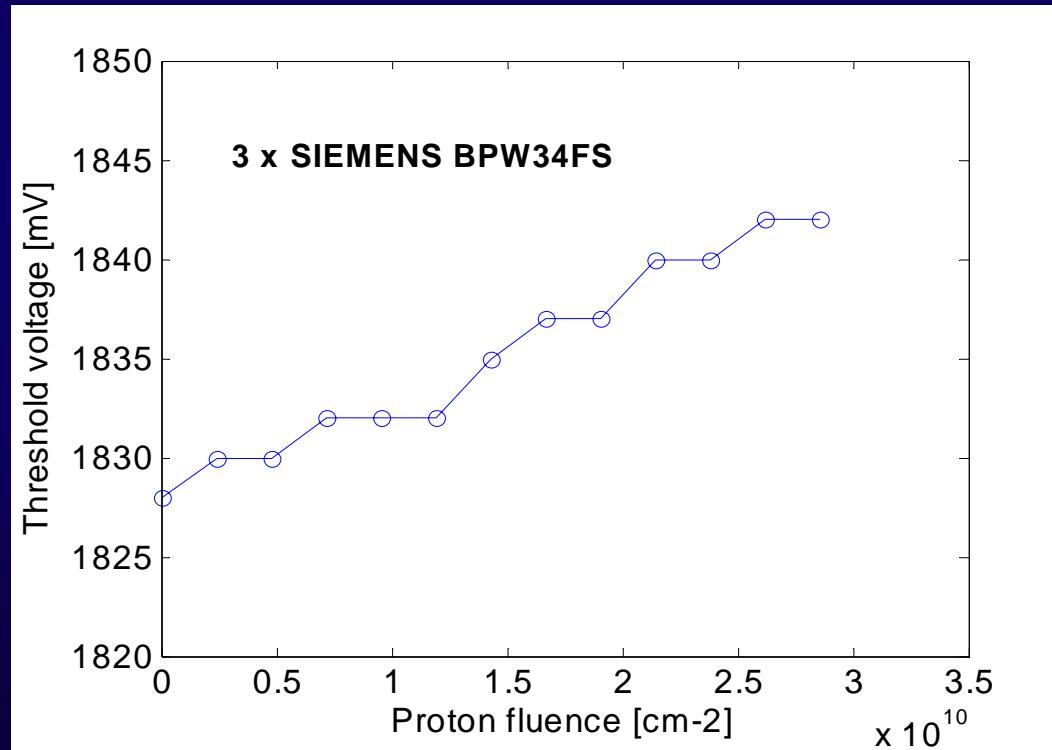


Irradiation of a single diode



Pin Diode - response to 250 MeV protons

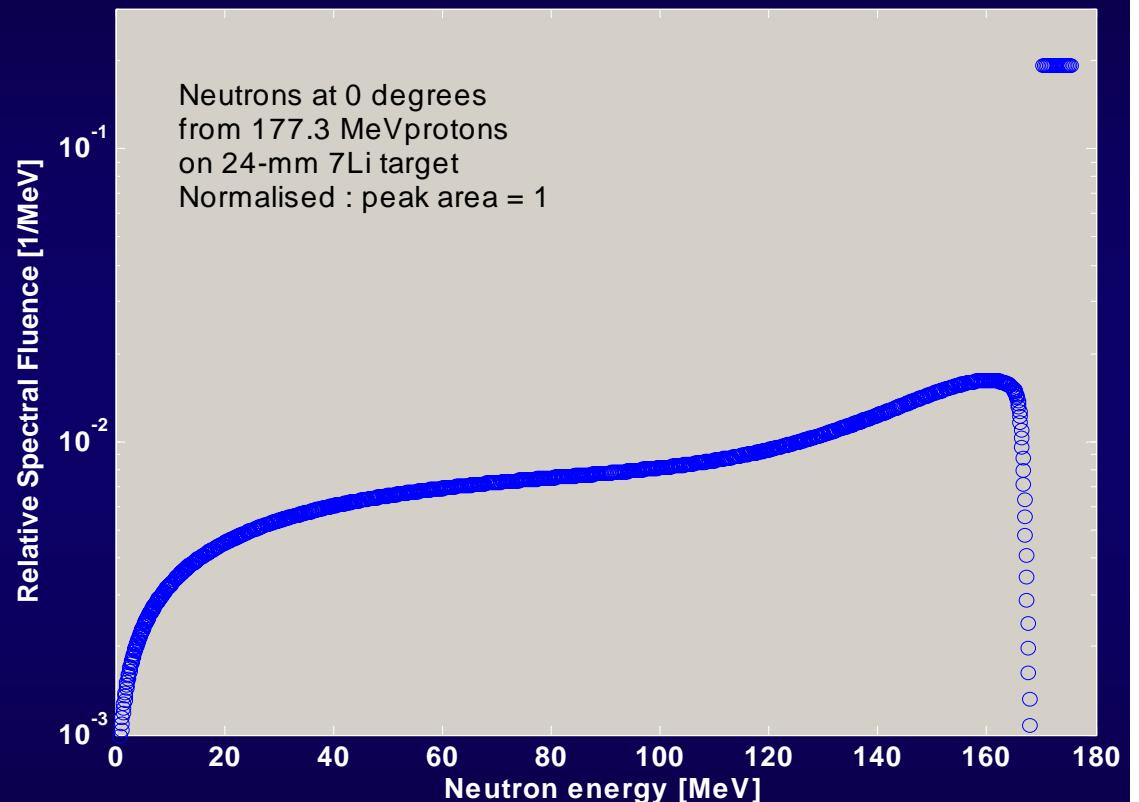
- Improved resolution for **RADMON** monitors
 - pre-irradiation with $4 \times 10^{12} \text{ n/cm}^2$ at 1 MeV
 - 3 diodes in series – thermo compensated



RADMON radiation tests – 173 MeV neutrons

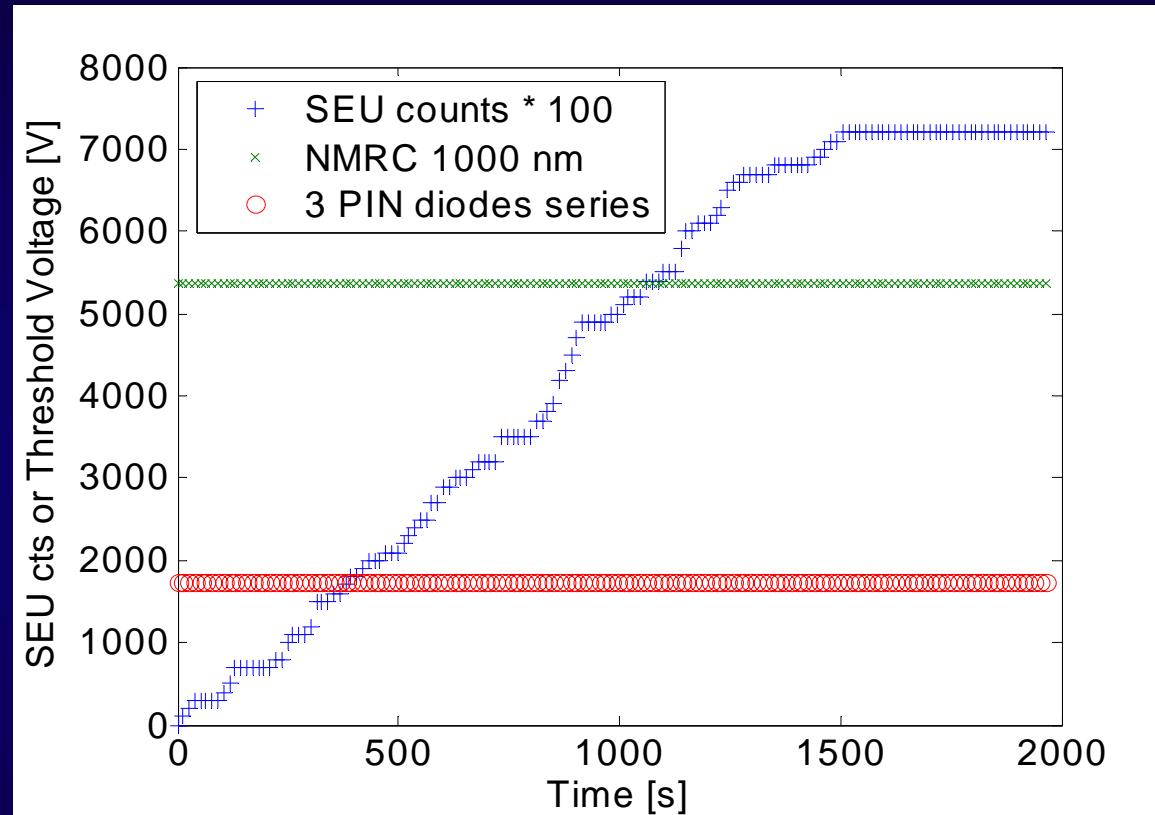


TSL Uppsala, Sweden



A.V. Prokofiev, M.B. Chadwick, S.G. Mashnik, N. Olsson, and L.S. Waters.
Journal of Nuclear Science and Technology, Supplement 2, pp.112-115 (2002)

RADMON - response to 173 MeV neutrons



- Fluence : $1.5 \times 10^8 \text{ cm}^{-2}$
- Flux : $1 \times 10^5 \text{ cm}^{-2} \text{ s}^{-1}$

Summary

- **NMRC Radfets**
 - *Radiation response sufficiently well understood*
 - *3 types (gate oxide thickness) allows for flexibility*
 - *2 radfets in // to improve range and resolution*
- **SEU counters**
 - *Time resolution to radiation monitoring*
 - *3 V : high resolution, increased uncertainty*
 - *5 V : reduced resolution, high precision*
 - *Total Dose effects visible below 200 Gy*
- **PIN diodes**
 - *Linear response to 1 MeV neutrons after $\sim 3 \times 10^{12}$ neutrons*
 - *Low fading at room temperature*
 - *Very small variation of Temperature coefficient with n fluence*
 - *Use of 3 pre irradiated diodes in // to provide :*
 - *improved resolution*
 - *remove initial threshold*